

Solder Materials

CORED WIRE

Product Name	Description	Key Attributes	Approximate Flux Content (% by Weight)	Diameter Range (mm)	Pb-Free Alloy	SnPb Alloy	IPC J-STE-004B Classification
Halogen-Free, No-Clean							
LOCTITE C 400	Cored solder wire	<ul style="list-style-type: none"> • Clear residue • Increased flux content for improved wetting on challenging surfaces • Award-winning multiple flux core technology that ensures consistent distribution of flux throughout the solder wire • Suitable for manual and robotic soldering 	2.2	0.38 – 1.63	<ul style="list-style-type: none"> • 90iSC • 99C • SAC305 • SAC387 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ROLO
Halide-Free, No-Clean							
LOCTITE C 502	Cored solder wire	<ul style="list-style-type: none"> • Clear residue • Good wetting on difficult substrates • Medium activity flux 	2.7	0.25 – 1.63	<ul style="list-style-type: none"> • 99C • SAC305 • SAC387 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ROM1
LOCTITE C 511	Cored solder wire	<ul style="list-style-type: none"> • Amber residue • Good wetting on difficult substrates • Heat stable • Medium activity flux 	2.7	0.38 – 1.63	<ul style="list-style-type: none"> • 99C • SAC305 • SAC387 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ROM1
Halide-Containing, Water Wash							
LOCTITE HYDX	Cored solder wire	<ul style="list-style-type: none"> • High activity flux • Excellent wetting on difficult substrates 	2.0	0.38 – 1.63	<ul style="list-style-type: none"> • 99C • SAC305 • SAC387 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ORH1

Solder Materials

LIQUID FLUX

Product Name	Description	Key Attributes	Solid Content (% by Weight)	Acid Value (mg KOH/g)	Application	IPC J-STE-004B Classification
Halide-Containing, Water Wash						
LOCTITE HYDX-20	Liquid Flux	<ul style="list-style-type: none"> Highly water soluble Residues designed to be cleaned with deionized water Solders onto copper, brass, nickel and mild steel efficiently Compatible with Pb-free and SnPb wave solder processes 	20	24	Spray/Foam	ORH1
Halide-Free, No-Clean						
LOCTITE MF 210	Liquid flux	<ul style="list-style-type: none"> Resin-free flux designed to solder onto surfaces known to have poor solderability Recommended for applications where high throughput is required Compatible with Pb-free and SnPb wave solder processes 	2.9	22.5	Spray/Foam	ORM0
LOCTITE MF R301	Liquid flux	<ul style="list-style-type: none"> Higher solids flux for better wetting on surfaces known to have reduced solderability Minimizes bridging on complex geometries Fully Pb-free and dual wave compatible Solvent-based flux may be thinned with isopropyl alcohol (IPA) Compatible with Pb-free and SnPb wave solder processes 	6.0	40	Spray/Foam	ROM0
Halogen-Free, VOC-Free, No-Clean						
LOCTITE MF 300	Liquid flux	<ul style="list-style-type: none"> General-purpose, resin-free, water-based flux with special formulation designed to minimize solder balling Compatible with Pb-free and SnPb wave solder processes 	4.6	37	Spray/Foam	ORM0
Halogen-Free, No-Clean						
LOCTITE MF 390HR	Liquid flux	<ul style="list-style-type: none"> Exceptional through-hole fill Recommended for automotive applications and general electrical soldering applications Compatible with Pb-free and SnPb wave solder processes 	6.0	20 – 25	Spray/Foam	ROLO

SOLDER PASTE

Product Name	Description	Key Attributes	Alloy	Particle Size Distribution	IPC J-STE-004B Classification	Optimal Shelf Life	Reflow Atmosphere
Temperature Stable, Halogen-Free, No-Clean							
LOCTITE GC 10	Pb-free, solder paste	<ul style="list-style-type: none"> RoHS-compliant Excellent resistance to high humidity Industry leader in paste transfer efficiency Improved stability at different storage and operating temperatures Extended stencil life up to 72 hr. Extended abandon time up to 24 hr. Suitable for high-density, small to large boards 	• SAC305	<ul style="list-style-type: none"> Type 3 Type 4 Type 4.5 (4A) Type 5 	ROLO	1 year at 26.5 °C	Designed for air; suitable with nitrogen
Halogen-Free, No-Clean							
LOCTITE HF 212	Pb-free, solder paste	<ul style="list-style-type: none"> High tack Low voiding RoHS-compliant Excellent fine pitch coalescence Designed for medium to large boards 	<ul style="list-style-type: none"> 90ISC SAC0307 SAC305 SAC387 	<ul style="list-style-type: none"> Type 3 Type 4 Type 4.5 (4A) Type 5 	ROLO	6 months at 0°C – 10°C	Air and nitrogen